

1.0 Features

- Generates up to nine clock outputs, grouped as 4-4-1 from one reference clock input
- Pin enable/disable of two banks of four clocks
- Auto power-down shuts off PLL, brings outputs low in the absence of any REF input
- Tracking skew < 200ps (spread-spectrum tolerant)
- Input-to-output propagation delay < 200ps
- Available in a 16-pin 0.150" SOIC

Table 1: Clock Enable Configuration

| CONTROL | | CLOCK OUTPUTS (MHz) | | | | |
|---------|----|---------------------|----------|--------|--------|--|
| S2 | S1 | CLK_A1:4 | CLK_B1:4 | CLK_FB | Source | |
| 0 | 0 | Tristate | Tristate | Driven | PLL | |
| 0 | 1 | Driven | Tristate | Driven | PLL | |
| 1 | 0 | Driven | Driven | Driven | REF | |
| 1 | 1 | Driven | Driven | Driven | PLL | |

Figure 1: Block Diagram

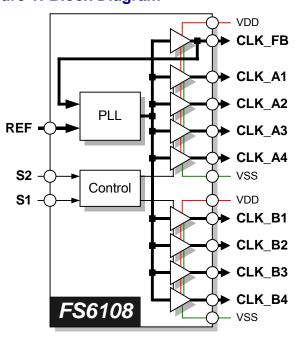
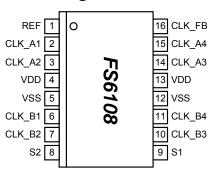


Table 2: Pin Descriptions

Key: DI = Digital Input; DI U = Input with Internal Pull-Up; DI $_{D}$ = Input with Internal Pull-Down; DIO = Digital Input/Output; DO = Digital Output; P = Power/Ground; # = Active-low pin

| PIN | TYPE | NAME | DESCRIPTION | | | | |
|-------|-----------------|--------|---|---------|--|--|--|
| 2 | DO_D | CLK_A1 | Clock output | | | | |
| 3 | DO_D | CLK_A2 | Clock output | Bank A | | | |
| 14 | DO_D | CLK_A3 | Clock output | Dalik A | | | |
| 15 | DO _D | CLK_A4 | Clock output | | | | |
| 6 | DO_D | CLK_B1 | Clock output | | | | |
| 7 | DO _D | CLK_B2 | Clock output | Bank B | | | |
| 10 | DO _D | CLK_B3 | Clock output | Dalik D | | | |
| 11 | DO_D | CLK_B4 | Clock output | | | | |
| 16 | DO _D | CLK_FB | Clock output that also provides an internal feedback connection to the PLL | | | | |
| 1 | DI_D | REF | Reference clock input | | | | |
| 8, 9 | DI ^U | S2, S1 | Two select inputs that enable and disable the clock outputs, and enable or bypass the PLL | | | | |
| 4, 13 | Р | VDD | 3.3V power supply | | | | |
| 5, 12 | Р | VSS | Ground | | | | |

Figure 2: Pin Configuration



FS6108-01

1:9 Zero Delay Buffer IC



May 2000

2.0 Electrical Specifications

Table 3: Absolute Maximum Ratings

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. These conditions represent a stress rating only, and functional operation of the device at these or any other conditions above the operational limits noted in this specification is not implied. Exposure to maximum rating conditions for extended conditions may affect device performance, functionality, and reliability.

| PARAMETER | SYMBOL | MIN. | MAX. | UNITS |
|--|-----------------|----------------------|----------------------|-------|
| Supply Voltage (V _{SS} = ground) | V_{DD} | V _{SS} -0.5 | 7 | V |
| Input Voltage, dc | Vı | V _{SS} -0.5 | V _{DD} +0.5 | V |
| Output Voltage, dc | Vo | V _{SS} -0.5 | V _{DD} +0.5 | V |
| Input Clamp Current, dc (V _I < 0 or V _I > V _{DD}) | I _{IK} | -50 | 50 | mA |
| Output Clamp Current, dc (V _I < 0 or V _I > V _{DD}) | I _{OK} | -50 | 50 | mA |
| Storage Temperature Range (non-condensing) | Ts | -65 | 150 | °C |
| Ambient Temperature Range, Under Bias | T _A | -55 | 125 | °C |
| Junction Temperature | T _J | | 125 | °C |
| Lead Temperature (soldering, 10s) | | | 260 | °C |
| Input Static Discharge Voltage Protection (MIL-STD 883E, Method 3015.7) | | | 2 | kV |



CAUTION: ELECTROSTATIC SENSITIVE DEVICE

Permanent damage resulting in a loss of functionality or performance may occur if this device is subjected to a high-energy electrostatic discharge.

Table 4: Operating Conditions

| PARAMETER | SYMBOL | CONDITIONS/DESCRIPTION | MIN. | TYP. | MAX. | UNITS |
|-----------------------------|------------------|----------------------------|------|------|-------|-------|
| Supply Voltage | V_{DD} | | 3.0 | 3.3 | 3.6 | V |
| Operating Temperature Range | T _A | | 0 | | 70 | °C |
| Load Capacitance | C _L | CLK_A1:4, CLK_B1:4, CLK_FB | | | 30 | pF |
| Reference Frequency Range | f _{REF} | | 10 | | 66.67 | MHz |



Table 5: DC Electrical Specifications

Unless otherwise stated, all power supplies = 3.6V, no load on any output, and ambient temperature range $T_A = 0^{\circ}\text{C}$ to 70°C . Parameters denoted with an asterisk (*) represent nominal characterization data and are not currently production tested to any specific limits. MIN and MAX characterization data are $\pm 3\sigma$ from typical. Negative currents indicate current flows out of the device.

| PARAMETER | SYMBOL | CONDITIONS/DESCRIPTION | MIN. | TYP. | MAX. | UNITS |
|--|------------------|--|----------------------|------|----------------------|---------------|
| Overall | | | | | | ji |
| Supply Current, Dynamic, with Loaded Outputs | I _{DD} | f _{REF} = 66.6MHz; all supplies = 3.465V | | 36 | | mA |
| Supply Current, Static | I _{DDs} | REF stopped either high or low | | 20 | | μА |
| Reference Input (REF) | | | | | | |
| High-Level Input Voltage | V _{IH} | | 2.0 | | V _{DD} +0.3 | V |
| Low-Level Input Voltage | V _{IL} | | V _{SS} -0.3 | | 0.8 | V |
| High-Level Input Current (pull-down) | I _{IH} | V _{IH} = 3.3V | | 25 | | μΑ |
| Low-Level Input Current | I _{IL} | | -1 | | 1 | μΑ |
| Digital Inputs (S1, S2) | | | | | | |
| High-Level Input Voltage | V _{IH} | | 2.0 | | V _{DD} +0.3 | V |
| Low-Level Input Voltage | V _{IL} | | V _{SS} -0.3 | | 0.8 | V |
| High-Level Input Current | I _{IH} | | -1 | | 1 | μΑ |
| Low-Level Input Current (pull-up) | I _{IL} | V _{IL} = 0V | | -30 | | μА |
| Clock Outputs (CLK_A1:4, CLK_B1:4, C | LK_FB) | | | | | |
| High Level Output Source Current | I _{OH} | V _O = 2.4V | -7 | -65 | | mA |
| Low Level Output Sink Current | I _{OL} | V _O = 0.4V | | 26 | 7 | mA |
| Output Impedance | Z _{OL} | Measured at 1.5V, output driving low | | 20 | | Ω |
| Output impedance | Z _{OH} | Measured at 1.5V, output driving high | | 18 | | 52 |
| Tristate Output Current | l _{OZ} | | -10 | | 10 | μΑ |
| Short Circuit Output Source Current | I _{OSH} | V_{DD} = 3.6V, V_{O} = 0V; shorted for 30s, max. | | -96 | | mA |
| Short Circuit Output Sink Current | I _{OSL} | $V_{DD} = V_O = 3.6V$, shorted for 30s, max. | | 90 | | mA |

Table 6: AC Timing Specifications

Unless otherwise stated, all power supplies = 3.6V, no load on any output, and ambient temperature range T_A = 25°C. Parameters denoted with an asterisk (*) represent nominal characterization data and are not currently production tested to any specific limits. MIN and MAX characterization data are $\pm 3\sigma$ from typical.

| PARAMETER | SYMBOL | CONDITIONS/DESCRIPTION | MIN. | TYP. | MAX. | UNITS |
|---------------------------------|---------------------|---|------|------|------|-------|
| Clock Outputs (CLK_A1:4, CLK_B1 | :4, CLK_FB) | | | | | |
| Duty Cycle * | d _t | Ratio of high pulse width to one clock period, measured at 1.5V | 45 | | 55 | % |
| Jitter, Period (peak-peak) * | $t_{j(\Delta P)}$ | From rising edge to rising edge at 1.5V, C _L =30pF | | 75 | | ps |
| Skew, Tracking | t _{sk(tr)} | ±0.5% non-linear (Lexmark) profile @ 31.5kHz | | 190 | | ps |
| Skew, Bank Output-Bank Output | t _{sk(b)} | CLK_A2 to CLK_B1; C _L =30pF | | 250 | | ps |
| PLL Reference Zero Delay | tφ | REF to CLK_FB | | 150 | | ps |
| Rise Time * | t _r | Measured @ 0.8V – 2.0V; C _L =30pF | | 1.6 | | ns |
| Fall Time * | t _f | Measured @ 2.0V - 0.8V; C _L =30pF | | 1.0 | | ns |



3.0 Package Information

Table 7: 16-pin SOIC (0.150") Package Dimensions

| | DIMENSIONS | | | | | |
|----|------------|--------|-------------|-------|--|--|
| | INC | HES | MILLIMETERS | | | |
| | MIN. | MAX. | MIN. | MAX. | | |
| Α | 0.061 | 0.068 | 1.55 | 1.73 | | |
| A1 | 0.004 | 0.0098 | 0.102 | 0.249 | | |
| A2 | 0.055 | 0.061 | 1.40 | 1.55 | | |
| В | 0.013 | 0.019 | 0.33 | 0.49 | | |
| С | 0.0075 | 0.0098 | 0.191 | 0.249 | | |
| D | 0.386 | 0.393 | 9.80 | 9.98 | | |
| Е | 0.150 | 0.157 | 3.81 | 3.99 | | |
| е | 0.050 | BSC | 1.27 | BSC | | |
| Н | 0.230 | 0.244 | 5.84 | 6.20 | | |
| h | 0.010 | 0.016 | 0.25 | 0.41 | | |
| L | 0.016 | 0.035 | 0.41 | 0.89 | | |
| Θ | 0° | 8° | 0° | 8° | | |

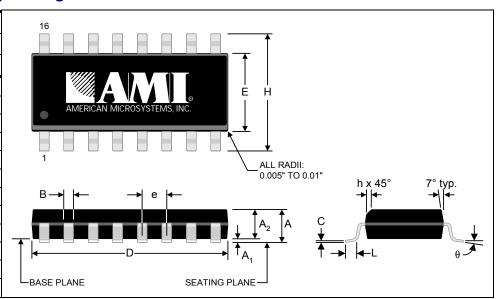


Table 8: 16-pin SOIC (0.150") Package Characteristics

| PARAMETER SYMBOL CONDITIONS/DESCRIPTION | | TYP. | UNITS | | |
|---|-----------------|-------------------------------|-------|------|--|
| Thermal Impedance, Junction to Free-Air | Θ_{JA} | Air flow = 0 m/s | 109 | °C/W | |
| Lead Inductance, Self | L ₁₁ | Corner lead | 4.0 | nH | |
| Lead inductance, Sen | | Center lead | 3.0 | | |
| Lead Inductance, Mutual | L ₁₂ | Any lead to any adjacent lead | 0.4 | nH | |
| Lead Capacitance, Bulk | C ₁₁ | Any lead to V _{SS} | 0.5 | pF | |



4.0 Ordering Information

Table 9: Device Ordering Codes

| DEVICE NUMBER | ORDERING CODE | PACKAGE TYPE | OPERATING TEMPERATURE RANGE | SHIPPING CONFIGURATION |
|---------------|---------------|----------------------|--------------------------------|---------------------------|
| FS6108-01 | 12055-801 | 16-pin (0.150") SOIC | 0° C to 70° C (Commercial) | Tape and Reel |
| F30100-01 | 12055-801 | 16-pin (0.150") SOIC | 0° C to 70° C (Commercial) | Tubes |

Copyright © 2000 American Microsystems, Inc.

Devices sold by AMI are covered by the warranty and patent indemnification provisions appearing in its Terms of Sale only. AMI makes no warranty, express, statutory implied or by description, regarding the information set forth herein or regarding the freedom of the described devices from patent infringement. AMI makes no warranty of merchantability or fitness for any purposes. AMI reserves the right to discontinue production and change specifications and prices at any time and without notice. AMI's products are intended for use in commercial applications. Applications requiring extended temperature range, unusual environmental requirements, or high reliability applications, such as military, medical life-support or life-sustaining equipment, are specifically not recommended without additional processing by AMI for such applications.

American Microsystems, Inc., 2300 Buckskin Rd., Pocatello, ID 83201, (208) 233-4690, FAX (208) 234-6796, WWW Address: http://www.amis.com E-mail: tgp@amis.com